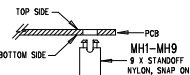


**NOTES: UNLESS OTHERWISE SPECIFIED**

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-810.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATION OF OMT SHALL BE INDICATED BY FREE OF SOLDER MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QP STAMP TO BOARD.
7. INSTALL PK PINS ON J21 PIN 11 AND J26 PINS 4 AND 5 AS SHOWN ON TOP ASSEMBLY DRAWING. REFER TO ASSY PK\_EXP04
8. INSTALL 9 STANDOFFS AS SHOWN BELOW:



DC3017A FOR DC3017A-A: COMBINE WITH LAYER 26 WITH LAYER 19  
FOR DC3017A-B: COMBINE WITH LAYER 26 WITH LAYER 20

<b>APPROVALS</b> PCB DES.    KEN WUI APP ENG.    ERIC H		 <b>ANALOG DEVICES</b> <a href="http://www.analog.com">www.analog.com</a>		 <b>POWER BY LINEAR</b> (408) 432-9800	
		TITLE: TOP ASSEMBLY DRAWING 24-PORT IEEE 802.3bt PSE MOTHER BOARD			
		SIZE    IC NO. N/A    LT3639		REV. 3	
SCALE = NONE		FILENAME: DC5017A-3		SH1 OF 2	